IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

B. Kim et al.

Attorney Docket No.: SEMT119849

Application No.: 10/700,782

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Examiner: E. Wong

Title:

BATH AND METHOD FOR HIGH RATE COPPER DEPOSITION

AMENDMENT AFTER NON-FINAL REJECTION

Seattle, Washington 98101

October 25, 2007

TO THE COMMISSIONER FOR PATENTS:

INTRODUCTORY COMMENTS

In response to the non-final Office Action mailed April 25, 2007, applicants submit the following amendments and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of the claims, which begins on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.